

## SPECIFICATIONS

# PXle-1486

## PXI FlexRIO FPD-Link Interface Module

This document lists the specifications for the following variants of the PXIe-1486:

- PXIe-1486 FlexRIO FPD-Link III Deserializer
- PXIe-1486 FlexRIO FPD-Link III Serializer
- PXIe-1486 FlexRIO FPD-Link III SerDes



**Note** If you purchased the PXIe-1486 as part of an NI system, refer to your system documentation for application-specific specifications.

## Definitions

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*Warranted* specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

*Characteristics* describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- *Typical* specifications describe the performance met by a majority of models.
- *Nominal* specifications describe an attribute that is based on design, conformance testing, or supplemental testing.
- *Measured* specifications describe the measured performance of a representative model.

Specifications are *Typical* unless otherwise noted.

## Conditions

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Specifications are valid under the following conditions unless otherwise noted.

- Ambient temperature of 23 °C ±5 °C
- Installed in chassis with slot cooling capacity ≥58 W<sup>1</sup>

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<sup>1</sup> The PXIe-1486 SerDes module can operate in a chassis with a slot cooling capacity of <58 W in a restricted user mode.

# Serial Device Compatibility

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Refer to the following information to verify that the PXIe-1486 module chip set is compatible with your serial device or camera.

Chip set brand	Texas Instruments
Module deserializer	DS90UB954
Module serializer	DS90UB953



**Note** Contact the manufacturer of your serial device or camera for details on compatibility with the PXIe-1486 module.

## Bus Interface

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Form factor	PCI Express Gen-3 x8
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## Reconfigurable FPGA

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The following table lists the specifications for the PXIe-1486 FPGA.

FPGA	KU11P
LUTs	298,560
DSP48 slices (25 × 18 multiplier)	2,928
Embedded Block RAM	21 Mb
Timebase reference sources	PXI Express 100 MHz (PXIe_CLK100)
Data transfers	DMA, interrupts, programmed I/O
Embedded UltraRAM™	22 Mb
Number of DMA channels	60



**Note** These values reflect the total number of FPGA resources available on the part. The number of resources available to the user is slightly lower, as some FPGA resources are consumed by board-interfacing IP for PCI Express, device configuration, and various board I/O. For more information, contact NI support.

## Onboard DRAM

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Memory size	4 GB (2 banks of 2 GB)
DRAM clock rate	1064 MHz
Physical bus width	32 bit

LabVIEW FPGA DRAM clock rate	267 MHz
LabVIEW FPGA DRAM bus width	256 bit per bank
Maximum theoretical data rate	17 GB/s (8.5 GB/s per bank)

## Serial I/O Characteristics

### Input Channels

Connector label	SI
Connector type	FAKRA Male Code Z, coaxial
PoC output range, AUX power maximum	9 V to 30 V, 800 mA per channel
PoC output range, internal power supply	
Nominal voltage	12 V
Maximum current	400 mA per channel, 2 A total
I/O standard	FPD-Link III with power over coax (PoC)
Maximum data rate	4.16 Gb/s
Reference clock speed	23 MHz to 26 MHz

### Output Channels

Connector label	SO
Connector type	FAKRA Male Code Z, coaxial
PoC input range	
Nominal voltage	9 V to 30 V
Maximum current	800 mA per channel
I/O standard	FPD-Link III with power over coax (PoC)
Maximum data rate	4.16 Gb/s
Reference clock speed	25 MHz to 104 MHz

### AUX Power Channels

Power sink or source maximum voltage	9 V to 30 V
Power sink or source maximum current	800 mA per channel
Power connector type	Conn Terminal Block, Weidmuller part number 2439690000
Power connector wiring	
Gauge	0.08 mm <sup>2</sup> to 0.5 mm <sup>2</sup> (28 AWG to 20 AWG)
Wire strip length	8 mm

Terminal connection type	Tension clamp
Retention	External strain relief of AUX power connections recommended

## PXle-1486 Deserializer

Input channels	8
Communication	I2C, GPIO, CSI-2
CSI-2 interface	4 lane, 800 Mbps per lane, no lane swaps or inversions

## PXle-1486 Serializer

Output channels	8
Communication	I2C, GPIO, CSI-2
CSI-2 interface	4 lane, 800 Mbps per lane, no lane swaps or inversions

## PXle-1486 SerDes

Input channels	4
Output channels	4
Maximum Tap pairs per module	4
Communication	I2C, GPIO, CSI-2
CSI-2 interface	4 lane, 800 Mbps per lane, no lane swaps or inversions

## Power Requirements



**Note** Power requirements are dependent on the contents of the LabVIEW FPGA VI used in your application.



**Note** Do not position product so that it is difficult to disconnect power.



**Note** If you are powering the PXle-1486 using your PXle chassis backplane, refer to the chassis specifications for detailed information about your internal power supply.

## Backplane Power Source

**Table 1.** Backplane Power

Voltage (V)	Maximum Current (A)
3.3	3.0
12	6.0

Total power 82 W, maximum

### Power over Coax (PoC) Source

#### External power supply

Voltage range 9 V to 30 V

Maximum current 800 mA per channel, up to 8 channels

#### Internal power supply

Nominal voltage 12 V

Maximum current 400 mA per channel, up to 2 A total

#### Diagnostic PoC measurement

Current measurement range 50 mA to 800 mA

#### Current measurement accuracy

50 mA to 100 mA ±20%

100 mA to 800 mA ±15%

Voltage measurement range 9 V to 30 V

Voltage measurement accuracy<sup>2</sup> ±5%

## Environmental Characteristics

### Temperature

Operating 0 °C to 55 °C<sup>3</sup>

Storage -40 °C to 71 °C

<sup>2</sup> Due to resistive (IR drop) losses in the circuit, actual voltage measurement accuracy depends on the load of the PoC circuit.

<sup>3</sup> The PXIe-1486 requires a chassis with slot cooling capacity  $\geq 58$  W. Not all chassis with slot cooling capacity  $\geq 58$  W can achieve this ambient temperature range. Refer to the [PXI Chassis Manual](#) for specifications to determine the ambient temperature ranges your chassis can achieve.

## Humidity

Operating	10% to 90%, noncondensing
Storage	5% to 95%, noncondensing
Pollution Degree	2
Maximum altitude	2,000 m (800 mbar) (at 25 °C ambient temperature)
Shock and Vibration	
Operating vibration	5 Hz to 500 Hz, 0.3 g RMS
Non-operating vibration	5 Hz to 500 Hz, 2.4 g RMS
Operating shock	30 g, half-sine, 11 ms pulse

## Physical

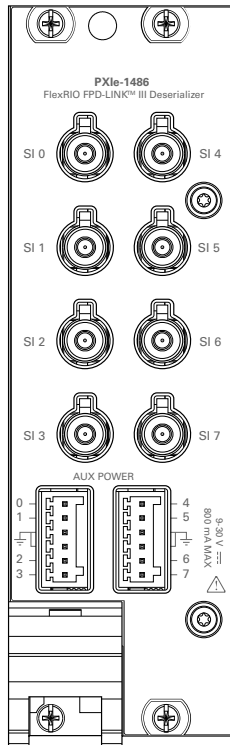
Dimensions	3U, two-slot PXI Express module, 21.6 cm × 4.1 cm × 13.0 cm (8.5 in. × 1.6 in. × 5.1 in.)
Weight	692 g (24.38 oz)

## Timing and Synchronization

Timebase	100 MHz, shared by all ports, disciplined by PXI_Clk100
Trigger I/O source	PXI_Trig <0:7>

# PXIe-1486 Front Panels

**Figure 1.** PXIe-1486 Deserializer Front Panel



**Figure 2. PXIe-1486 Serializer Front Panel**

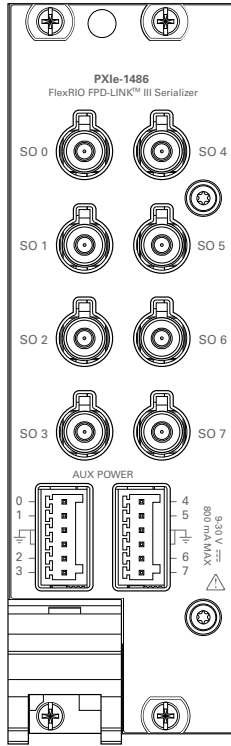
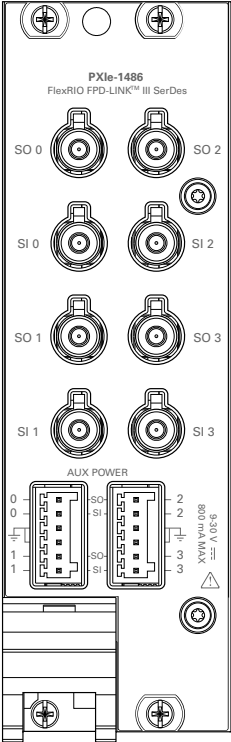




Figure 3. PXIe-1486 SerDes Front Panel



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